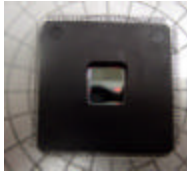
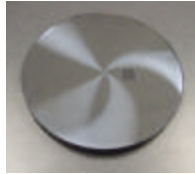


ULTRA TEC Selected Area Preparation Products

-- Package & sample application range



Plastic



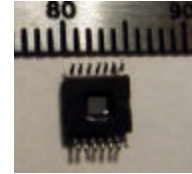
Wafer



Ceramic



Flip-chip



Small packages

u-BGA
F-BGA
L-BGA
T-BGA
P-BGA
FC-BGA

LQFP
TQFP
MQFP
QFN

TEM samples

SOIC
SSOP
TSOP
MSOP

TO-202
TO-92
TO-3
TO-220
TO-66
SOT

Hermetic seals

Flip-chip

Stack-die
MCP
CSP

8" Wafer
Wafer shards

Photonic Packages

Pre-FIB

PDIP

PLCC

PGA

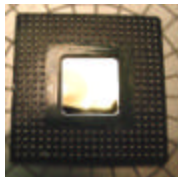
CDIP

CLCC

SIP

ZIL

GaAs / InP



BGA



leadless



Power Devices



Thick heat sink



Multi-layer PCB

If your package type is not listed here, please contact us to see how we can help

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